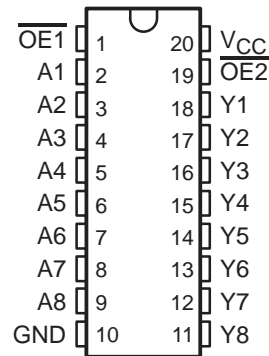


# SN54ABT540, SN74ABT540 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

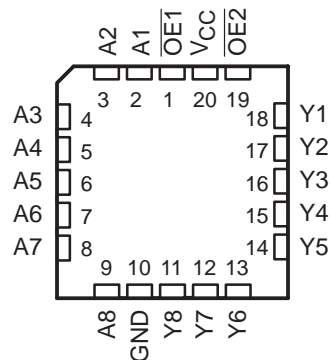
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- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical  $V_{OLP}$  (Output Ground Bounce) < 1 V at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$
- High-Drive Outputs (–32-mA  $I_{OH}$ , 64-mA  $I_{OL}$ )
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package

SN54ABT540 . . . J OR W PACKAGE  
SN74ABT540 . . . DB, DW, N, OR PW PACKAGE  
(TOP VIEW)



SN54ABT540 . . . FK PACKAGE  
(TOP VIEW)



## description

The 'ABT540 octal buffers and line drivers are ideal for driving bus lines or buffer memory address registers. The devices feature inputs and outputs on opposite sides of the package that facilitate printed circuit board layout.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ( $\overline{OE1}$  or  $\overline{OE2}$ ) input is high, all corresponding outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT540 is characterized for operation over the full military temperature range of  $-55^\circ\text{C}$  to  $125^\circ\text{C}$ . The SN74ABT540 is characterized for operation from  $-40^\circ\text{C}$  to  $85^\circ\text{C}$ .

FUNCTION TABLE

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	H
L	L	H	L
H	X	X	Z
X	H	X	Z



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 **TEXAS  
INSTRUMENTS**

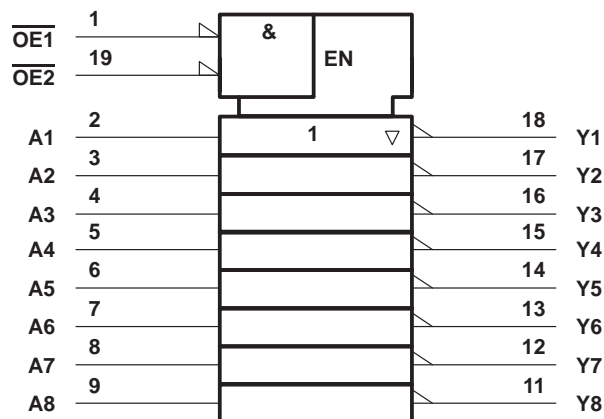
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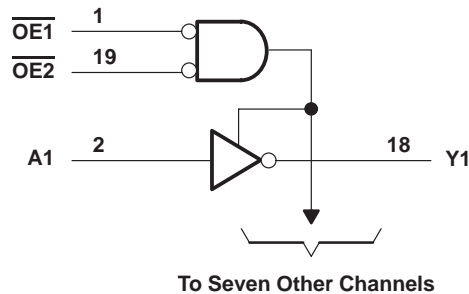
# SN54ABT540, SN74ABT540 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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## logic symbol†



## logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, $V_O$ .....	-0.5 V to 5.5 V
Current into any output in the low state, $I_O$ : SN54ABT540 .....	96 mA
SN74ABT540 .....	128 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	-18 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ ) .....	-50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DB package .....	115°C/W
DW package .....	97°C/W
N package .....	67°C/W
PW package .....	128°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

## recommended operating conditions (see Note 3)

		SN54ABT540		SN74ABT540		UNIT
		MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	4.5	5.5	4.5	5.5	V
$V_{IH}$	High-level input voltage	2		2		V
$V_{IL}$	Low-level input voltage		0.8		0.8	V
$V_I$	Input voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$	High-level output current		-24		-32	mA
$I_{OL}$	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5	5	ns/V
$T_A$	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

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# SN54ABT540, SN74ABT540 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T <sub>A</sub> = 25°C			SN54ABT540		SN74ABT540		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA	-1.2			-1.2		-1.2		V
V <sub>OH</sub>	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = -3 mA	2.5			2.5		2.5		V
	V <sub>CC</sub> = 5 V,	I <sub>OH</sub> = -3 mA	3			3		3		
	V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -24 mA	2			2				
I <sub>OH</sub> = -32 mA		2*					2			
V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA	0.55			0.55				V
		I <sub>OL</sub> = 64 mA	0.55*					0.55		
V <sub>hys</sub>			100							mV
I <sub>I</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = V <sub>CC</sub> or GND	±1			±1		±1		μA
I <sub>OZH</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.7 V	50			50		50		μA
I <sub>OZL</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0.5 V	-50			-50		-50		μA
I <sub>off</sub>	V <sub>CC</sub> = 0,	V <sub>I</sub> or V <sub>O</sub> ≤ 4.5 V	±100					±100		μA
I <sub>CEX</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high	50			50		50		μA
I <sub>O‡</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
I <sub>CC</sub>	V <sub>CC</sub> = 5.5 V, I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND	Outputs high	1	250		250		250		μA
		Outputs low	24	30		30		30		mA
		Outputs disabled	0.5	250		250		250		μA
ΔI <sub>CC</sub> §	Data inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	1.5			1.5		1.5		mA
		Outputs enabled	1.5			1.5		1.5		
	Control inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	0.05			0.05		0.05		
C <sub>i</sub>	V <sub>I</sub> = 2.5 V or 0.5 V			3					pF	
C <sub>o</sub>	V <sub>O</sub> = 2.5 V or 0.5 V			8					pF	

\* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V<sub>CC</sub> = 5 V.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			SN54ABT540		SN74ABT540		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	1	2.9	4.1	1		1	4.8	ns
t <sub>PHL</sub>			1	3.1	4.3	1		1	4.8	
t <sub>PZH</sub>	OE	Y	1.1	3.4	4.9	1.1		1.1	5.9	ns
t <sub>PZL</sub>			1.1	3	5.8	1.1		1.1	6.4	
t <sub>PHZ</sub>	OE	Y	1.5	5.3	6.8	1.5		1.5	7.3	ns
t <sub>PLZ</sub>			1.2	4.4	5.7	1.2		1.2	6.2	

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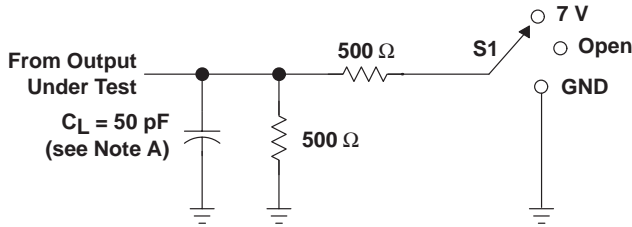


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**SN54ABT540, SN74ABT540**  
**OCTAL BUFFERS/DRIVERS**  
**WITH 3-STATE OUTPUTS**

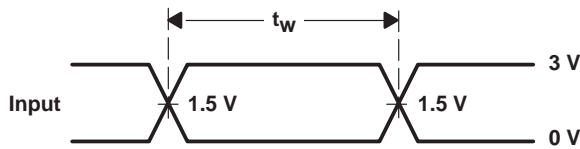
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**PARAMETER MEASUREMENT INFORMATION**

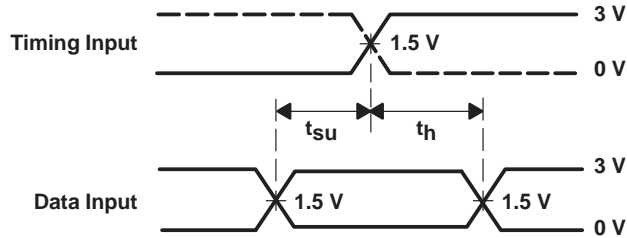


**LOAD CIRCUIT**

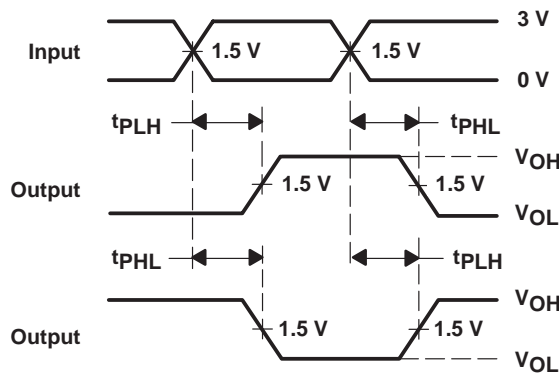
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open



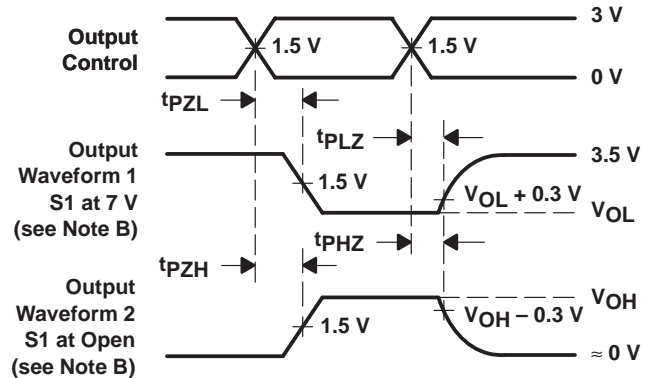
**VOLTAGE WAVEFORMS**  
**PULSE DURATION**



**VOLTAGE WAVEFORMS**  
**SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS**  
**PROPAGATION DELAY TIMES**  
**INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS**  
**ENABLE AND DISABLE TIMES**  
**LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .  
 D. The outputs are measured one at a time with one transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SN74ABT540DBR</a>	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB540
SN74ABT540DBR.B	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB540
SN74ABT540DBRG4	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB540
SN74ABT540DBRG4.B	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB540
<a href="#">SN74ABT540DW</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT540
SN74ABT540DW.B	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT540
<a href="#">SN74ABT540DWR</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT540
SN74ABT540DWR.B	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT540
<a href="#">SN74ABT540N</a>	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ABT540N
SN74ABT540N.B	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ABT540N
<a href="#">SN74ABT540NSR</a>	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT540
SN74ABT540NSR.B	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT540

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT540DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT540DBRG4	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT540DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ABT540NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT540DBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74ABT540DBRG4	SSOP	DB	20	2000	353.0	353.0	32.0
SN74ABT540DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74ABT540NSR	SOP	NS	20	2000	356.0	356.0	45.0



**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ABT540DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ABT540DW.B	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ABT540N	N	PDIP	20	20	506	13.97	11230	4.32
SN74ABT540N.B	N	PDIP	20	20	506	13.97	11230	4.32

# DB0020A



# PACKAGE OUTLINE

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4214851/B 08/2019

### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4214851/B 08/2019

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

# DW0020A



# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

# EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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